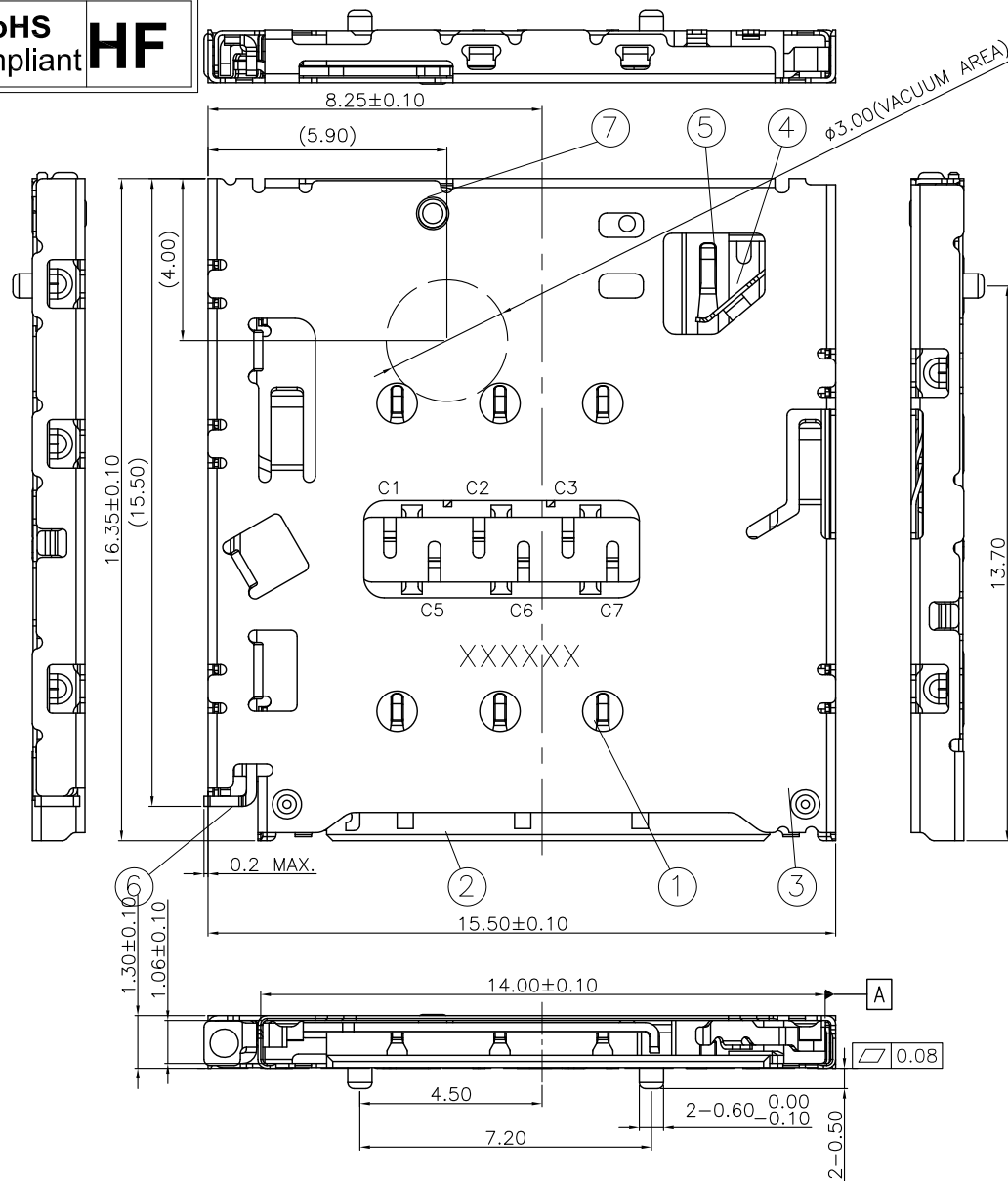


RoHS Compliant **HF**

REV.	ECN.NO.	MODIFY.CONTENT
X1		NEW



NOTES :

1. MATERIAL :
 - 1.1 HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - 1.2 SHELL: STAINLESS STEEL SUS304.
 - 1.3 CONTACT: COPPER ALLOY C5210.
2. FINISH :
 - 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, Au 1u"MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - 2.2 SHELL: 30u" MIN SOLDERABILITY NICKEL PLATING OVERALL. Au 1u"MIN ON SOLDERTAIL AREA.
3. ELECTRICAL CHARACTERISTICS:
 - 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
 - 3.2 CURRENT RATING : 0.5 A.
 - 3.3 OPERATING TEMPERATURE: -25°C~+85°C.
 - 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
 - 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

2.PART.NO.:

SP198-AN401-**

- 08: 功能区镀金1U", 锡脚Gold Flash
- 09: 功能区镀金3U", 锡脚Gold Flash
- 10: 功能区镀金5U", 锡脚Gold Flash
- 11: 功能区镀金15U", 锡脚Gold Flash
- 12: 功能区镀金30U", 锡脚Gold Flash

PIN ASSIGNMENT

SWITCH CIRCUIT

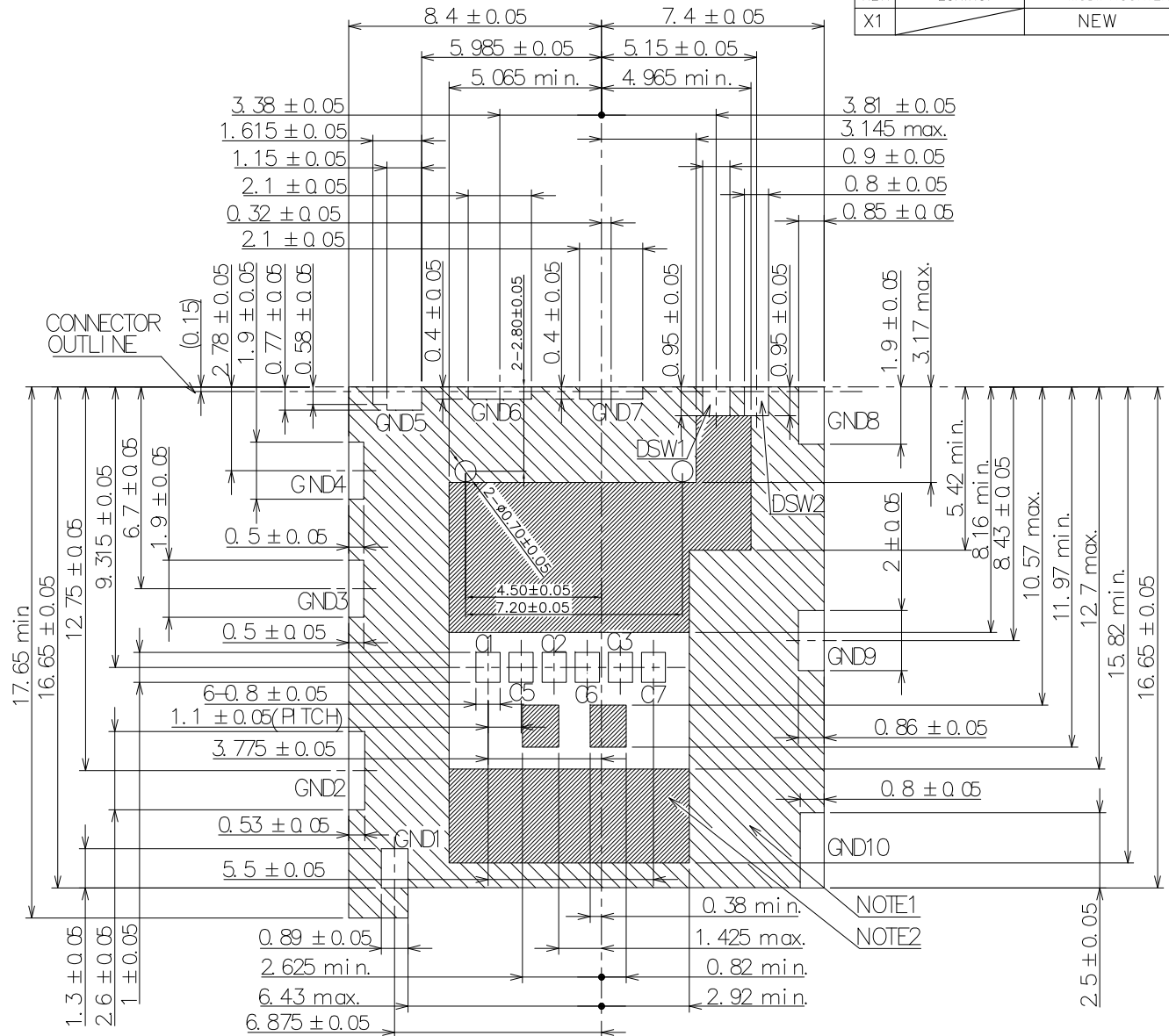
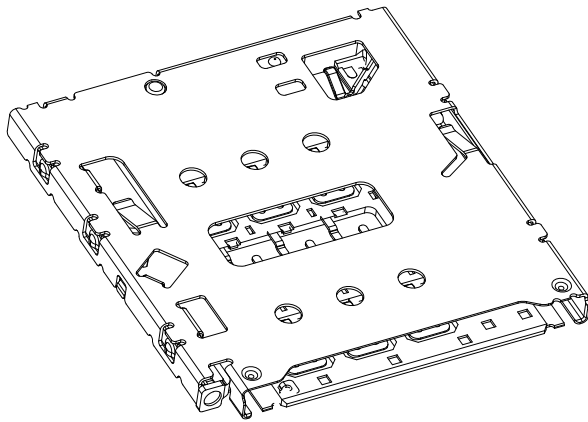
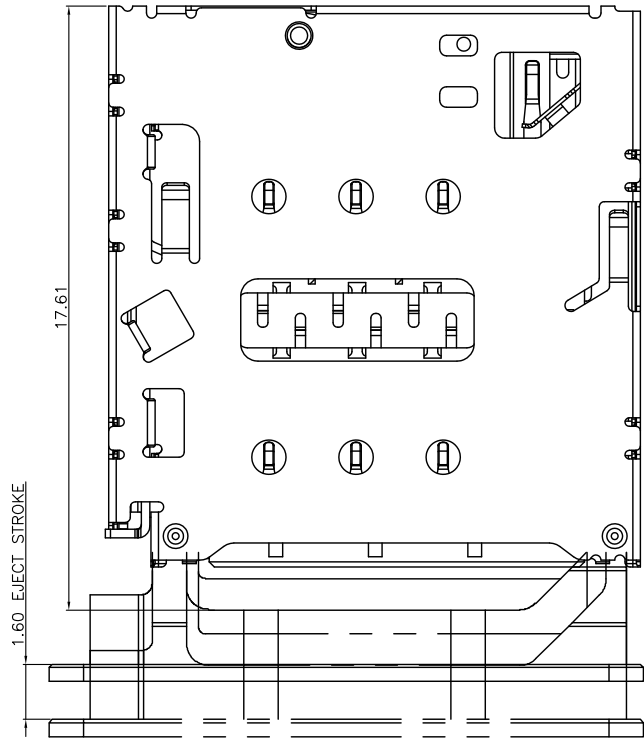
	WITHOUT TRAY	WITH TRAY	
	④ ⑤	④ ⑤	C1 Vcc
	↓	↓	C2 RST
DSW	GND	GND	C3 CLK
			C5 GND
			C6 Vpp
			C7 I/O

GENERAL TOLERANCE	TOLERANCE	DWG.NO.	SP198-AN401-00	PART.NO.	SP198-AN401-**	DRAWN	L.M.J 2021.06.11
x. ±0.50	x. *± 5°	REV.	X1	TITLE	Micro SIM With Tray HI.30-2	CHECKED	
.x±0.25	.x*± 2°	SIZE		SHEET	1 OF 3	APPROVED	
.xx±0.15	.xx± 1°	A4					


OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

RoHS Compliant **HF**

REV.	ECN.NO.	MODIFY.CONTENT
X1		NEW



RECOMMENDED P.C.B LAYOUT
TOP VIEW (TOLERANCE +/- 0.05)

GENERAL TOLERANCE		DWG.NO.	SP198-AN401-00	PART.NO.	SP198-AN401-**-	DRAWN	L.M.J 2021.06.11	UNIT	mm	SCALE	NO SCALE
x. ± 0.50	x. ° ± 5°	REV.	X1	TITLE	Micro SIM With Tray H1.30-2	CHECKED		 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x ± 0.25	.x ° ± 2°	SIZE	A4	SHEET	2 OF 3	APPROVED					
.xx ± 0.15	.xx ° ± 1°										